

REMARKS

Upon further review of the Amendment filed May 6, 2002, Applicants have amended claim 25 to provide claim 25 to be more consistent with the disclosure in the specification, for example, in the last paragraph on page 6 of Applicants' specification. Clearly, this amendment of claim 25 does not constitute new matter, and is clearly supported by the originally filed disclosure.

Entry of the present amendment and of the amendments in the Amendment filed May 6, 2002, and reconsideration and allowance of all claims then present in the application, are respectfully requested.

Attached hereto is a marked-up version of the changes made to the claims by the current Supplemental Amendment. This marked-up version is on the attached page which is captioned "VERSION WITH MARKINGS TO SHOW CHANGES MADE".

To the extent necessary, Applicants petition for an extension of time under 37 CFR 1.136. Please charge any shortage in fees due in connection with the

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filing of this paper, including extension of time fees, to the Deposit Account No. 01-2135 (Case No. 843.37558VX2) and please credit any excess fees to such Deposit Account.

Respectfully submitted,

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VERSION WITH MARKINGS TO SHOW CHANGES MADE
IN THE CLAIMS

Please amend the claims presently in the application as follows:

25. (Amended) A method of manufacturing a semiconductor integrated circuit device according to claim 17, wherein said cleaning is performed with the processing solution at a temperature as low as 40°C.